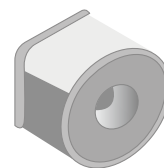
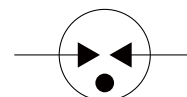


FEATURES

- | Surface Mounting Design 8.3*8.3*6.0mm
- | High Current Handling Capability 20000A @ 8/20 μ s
- | Low Capacitance and Insertion Loss
- | Quick Response and Long Service Life
- | Moisture sensitivity level: Level 1



8.3*8.3*6.0mm





Schematic Symbol

APPLICATION INFORMATION

- | Communication equipment.
- | Repeaters, Modems
- | Telephone Interface, Line cards.
- | Data communication equipment.

AGENCY APPROVALS

| Icon | Solderability |
|---|------------------------------------|
| RoHS | Compliance with 2011/65/EU |
| HF | Compliance with IEC61249-2-21:2003 |
|  | Mean lead free |
|  | UL Certificated E505857 |

PRODUCT CHARACTERISTICS

| Lead Material | Body Material | Terminal Finish |
|-----------------------|---------------|-----------------------|
| Copper or Fe-Ni alloy | Ceramics | 100% Matte-Tin Plated |

ELECTRICAL PARAMETER

| Parameter | Condition | Rating | Unit |
|-------------------------------------|----------------------|---|------------|
| DC Spark-over Voltage 1) | 100V/s | 376-564 | V |
| Impulse Spark-over Voltage | At 1kV/ μ s | for 99 % of measured values ≤ 1000 | |
| | At 1kV/ μ s | Typical values of distribution ≤ 950 | |
| Discharge Current (8/20 μ s) 2) | 10 times | 20 | KA |
| AC Discharge Current | 50Hz, 1S | 20 | A |
| Minimum Insulation Resistance | Test Voltage DC=250V | 1 | G Ω |
| Max. Capacitance 1MHz | $V_{DC}=0.5V$ | 1.5 | pF |
| Operating and Storage Temperature | | -40~125 | °C |

1) In ionized mode

2) Terms and waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21

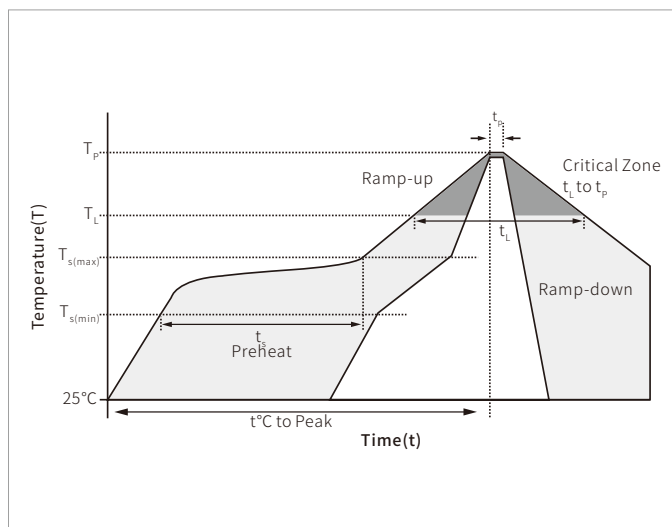
ENVIRONMENTAL RELIABILITY CHARACTERISTICS

| Testing items | Technical standards |
|-------------------------------|---|
| High Temperature Storage Test | Temperature: 85°C ; Time:2H |
| Low Temperature Storage Test | Temperature: -40°C ; Time:2H |
| Vibration | Frequency: 10-500Hz ; Amplitude:0.15mm ; Time:45min |
| Resistance of soldering heat | Temperature: 260 \pm 5°C; Time of dip soldering: 10s, 1time |

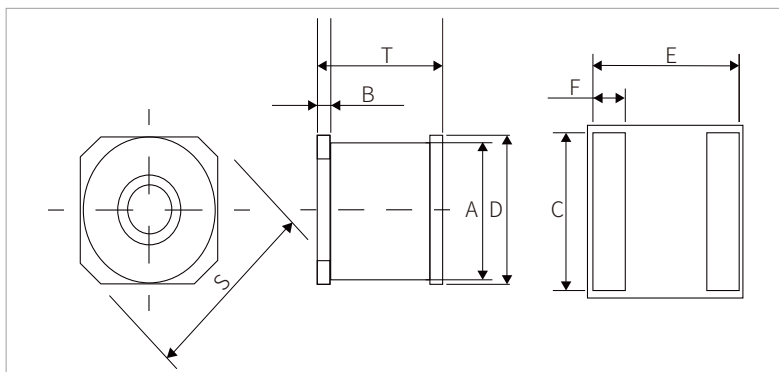
NOTE:Up-screen program can be specified by customer's request via contacting Semiware service

REFLOW PROFILE

| Reflow Condition | | Lead-free assembly |
|--|----------------------------------|--------------------|
| Pre Heat | Temperature Min | 150°C |
| | Temperature Max | 200°C |
| | Time(min to max) | 60 – 180 secs |
| Average ramp up rate (Liquidus)Temp (T_L) to peak $T_s(max)$ to T_L - Ramp-up Rate | | 3°C/second max |
| Reflow | Temperature (T_L) (Liquidus) | 217°C |
| | Time(min to max)(t_s) | 60 – 150 seconds |
| Peak Temperature (T_p) | | 260 °C |
| Time within 5°C of actual peak Temperature (t_p) | | 10-30 seconds |
| Ramp-down Rate | | 6°C/second max |
| Time 25°C to peak Temperature (T_p) | | 8 minutes max. |
| Do not exceed | | 260°C |

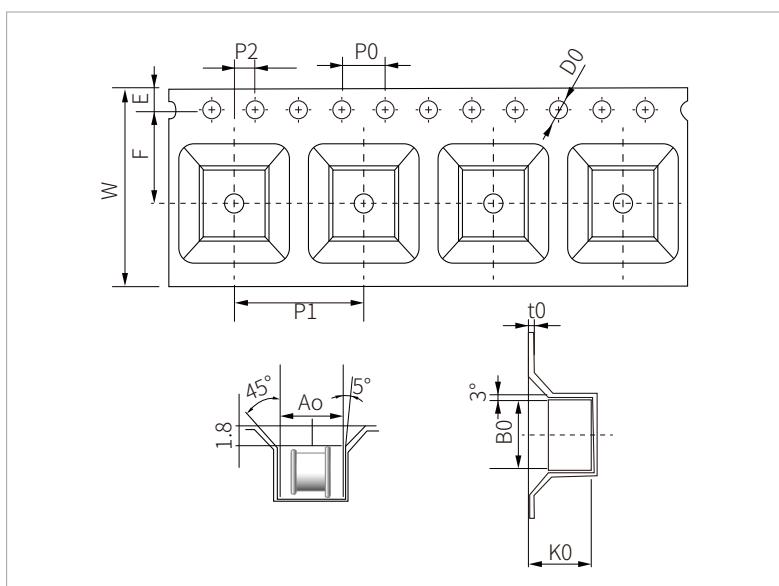


DIMENSIONS AND RECOMMENDED SOLDERING PAD



| Ref. | mm |
|------|----------------|
| A | 8.0 ± 0.2 |
| B | 0.5 ± 0.1 |
| C | 9.0 |
| D | 8.3 ± 0.2 |
| E | 6.7 |
| F | 1.2 |
| T | 6.0 ± 0.25 |
| S | 9.0 ± 0.4 |

PACKAGE REEL INFORMATION



| Ref. | mm |
|------|-----------------|
| W | 16.0 ± 0.3 |
| P0 | 4.0 ± 0.1 |
| P1 | 12.0 ± 0.1 |
| P2 | 2.0 ± 0.1 |
| D0 | 1.55 ± 0.05 |
| E | 1.75 ± 0.1 |
| F | 7.5 ± 0.1 |
| A0 | 6.35 ± 0.1 |
| K0 | 6.55 ± 0.1 |
| B0 | 8.65 ± 0.1 |
| t0 | 0.5 ± 0.1 |

ORDERING INFORMATION

| Part Number | Size | Marking | QTY/Reel | Reel Size |
|-------------|---------------|--|----------|-----------|
| SG2R08B470A | 8.3*8.3*6.0mm |  SG470 08 | 600 | 13" |

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By QR Code

Website



Wechat

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